L Number	Hits	Search Text	DB	Time stamp
-	0	"20030030153"	USPAT	2004/07/11 19:09
-	1	"20030030153"	USPAT; US-PGPUB	2004/07/11 19:32
-	2	"6018462"	USPAT; US-PGPUB	2004/07/11 19:34
-	1		USPAT	2004/07/11 19:33
-	1		USPAT	2004/07/11 19:34
-	1		USPAT	2004/07/11 19:34
-	1		USPAT	2004/07/11 19:34
-	1		USPAT	2004/07/11 19:34
-	1039147	pad with multi$4 with (under or lower) layer	USPAT; US-PGPUB	2004/07/11 19:35
-	1038997	pad with multi$4 near (under or lower) layer	USPAT; US-PGPUB	2004/07/11 19:36
-	0	pad with multi$4 near (under or lower) near layers	USPAT	2004/07/11 19:36
-	33	pad with multi$4 with (under or lower) near layers	USPAT	2004/07/11 19:49
-	1598	pad with multi$4 near layers	USPAT	2004/07/11 20:10
-	47	(pad with multi$4 near layers) and 257/781	USPAT	2004/07/11 20:10
-	9	"5378927"	USPAT	2004/07/11 20:00
-	203	pad with multi$4 near layers with (solder or ball or bump)	USPAT	2004/07/11 20:00
-	145	pad with multi$4 near layers with (solder)	USPAT	2004/07/11 20:01
-	26	(pad with multi$4 near layers) and 257/782	USPAT	2004/07/11 20:12
-	787	257/782	USPAT	2004/07/11 20:51
-	1296	257/779	USPAT	2004/07/11 20:51
-	1108	257/779 and solder	USPAT	2004/07/11 20:52
-	71	257/779 and solder and pad with (lower or bottom or multi$4) near (layer or film)	USPAT	2004/07/11 20:57
-	126	(257/779 or 257/780 or 257/781) and solder and pad with (lower or bottom or multi$4) near (layer or film)	USPAT	2004/07/11 21:04
-	1		USPAT	2004/07/11 20:59
-	1		USPAT	2004/07/11 21:00
-	1		USPAT	2004/07/11 21:00
-	1		USPAT	2004/07/11 21:00
-	1		USPAT	2004/07/11 21:00
-	1		USPAT	2004/07/11 21:01
-	1		USPAT	2004/07/11 21:01
-	2029	(semiconductor or die or chip or IC) and pad with (lower or bottom or multi$4) near (layers or films)	USPAT	2004/07/11 21:05
-	1123	(semiconductor or die or chip or IC) and pad with multi$4 near (layers or films)	USPAT	2004/07/11 22:05
-	711	(semiconductor or die or chip or IC) and pad with two near (layers or films)	USPAT	2004/07/11 22:05
-	3	(semiconductor or die or chip or IC) and pad with two near (lower or bottom) near (layers or films)	USPAT	2004/07/11 22:06
-	0	(semiconductor or die or chip or IC) and pad with three near (lower or bottom) near (layers or films)	USPAT	2004/07/11 22:06
-	4	(semiconductor or die or chip or IC) and pad with multi near (lower or bottom) near (layers or films)	USPAT	2004/07/11 22:07
-	834	(semiconductor or die or chip or IC) and pad with barrier near (layers or films)	USPAT	2004/07/11 22:08